

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-4 are pending in the present application, Claims 1-4 having been amended, and Claims 5-8 having been canceled without prejudice or disclaimer by the present amendment. Applicants respectfully submit that no new matter is added.¹

In the outstanding Office Action, Claims 1-4 were objected to as vague and confusing; and Claims 1-4 were rejected under 35 U.S.C. § 103(a) as unpatentable over Sasaki et al. (U.S. Patent Application Publication No. 2003/0038372 A1, hereinafter "Sasaki") in view of Traskos et al. (U.S. Patent No. 5,309,629, hereinafter "Traskos").

With respect to the claim objections, Claims 1-4 have been amended to remove the word "desired." Accordingly, Applicants respectfully request the withdrawal of the objections to Claims 1-4.

Independent Claim 1 stands rejected under 35 U.S.C. § 103(a) as unpatentable over Sasaki in view of Traskos. Applicants respectfully submit that the amended form of Claim 1 recites features not disclosed or rendered obvious by the applied references.

Independent Claim 1 recites a sheet forming method, including, in part, "a step of executing an exposure process . . . , executing a process for development-removing . . . , [and] executing an electro-depositing process using a substance having an electrical characteristic onto the portion with the photosensitive substance removed." Applicants submit that Sasaki and Traskos fail to disclose or suggest these features.

Sasaki concerns developing a photosensitive conductive material.² According to Sasaki, the unexposed component of the photosensitive conductive material is eliminated so

¹ The amendment to Claim 1 finds support at least in the specification at 12, ll. 23-27. The amendment to Claim 3 finds support at least in Claim 1 and in the specification at 25, l. 25, and in the paragraph beginning at 31, l. 19. The amendment to Claim 4 finds support at least in Claim 1 and in the specification in the paragraphs beginning at 14, ll. 11 and 27, and at 15, ll. 14-16.

as to form a lower conductor pattern layer.³ Further to Sasaki, an insulating material is applied so as to cover the lower conductor pattern layer via a method such as printing.⁴

Applicants submit that Sasaki fails to disclose or suggest “an *electro-depositing* process using a substance having an electrical characteristic onto the portion with the photosensitive substance removed,” as recited in amended Claim 1.

Traskos concerns a pattern of circuit traces formed on a mandrel.⁵ According to Traskos, the pattern may be formed on the mandrel by any suitable method such as electroless plating, electroplating, or vapor deposition.⁶

Applicants submit that Traskos fails to disclose or suggest “an electro-depositing process using a substance having an electrical characteristic *onto the portion with the photosensitive substance removed*,” as recited in amended Claim 1.

Accordingly, Sasaki and Traskos fail to disclose or suggest “a step of executing an exposure process . . . , executing a process for development-removing . . . , [and] executing an electro-depositing process using a substance having an electrical characteristic onto the portion with the photosensitive substance removed,” as recited in amended Claim 1.

Therefore, Claim 1 (and all associated dependent claims) patentably distinguishes over Sasaki and Traskos.

Independent Claim 3 recites a sheet forming method, including, “a process of making residual a part of the portion with the photosensitive substance removed in a way that *stops the depositing process halfway*, and depositing the photosensitive substance in place of the substance having the electrical characteristic on the residual part.” Applicants respectfully submit Sasaki and Traskos are silent regarding these features.

² Sasaki, para. [0049].

³ Id.

⁴ Id., para. [0050].

⁵ Traskos, col.8, ll.46-47.

⁶ Id., ll.47-51.

Independent Claim 4 recites a sheet forming method, including, in part,

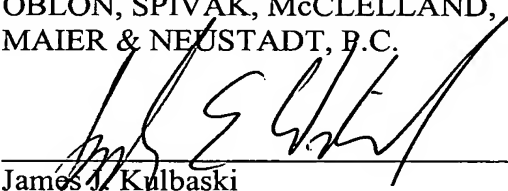
a step of executing an exposure process . . . , executing a process for development-removing . . . , executing a process of depositing a first substance having a first electrical characteristic onto the first pattern space so that a part of the first pattern space is rendered residual as a residual portion, ***depositing a second substance*** which has a second electronic characteristic and ***of which an unexposed portion is removed by the developer, onto the residual portion***, forming a second pattern space by exposing and developing the second substance, [and] depositing first, second, or other substance into the second pattern space

Applicants respectfully submit Sasaki and Traskos are silent regarding these features.

Consequently, in light of the above discussion and in view of the present amendment, the present application is believed to be in condition for allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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